# 900V N-Channel MOSFET

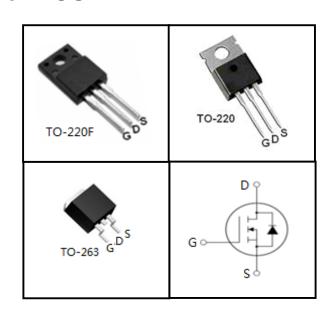
#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information				
Device	Package Marking			
CS2N90F	TO-220F	CS2N90F		
CS2N90P	TO-220	CS2N90P		
CS2N90B	TO-263	CS2N90B		



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted							
Parameter	Symbol	Value			Unit		
raidinetei	Symbol	TO-220F	TO-22	20 TO-263	Uilit		
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	900		V			
Continuous Drain Current	I <sub>D</sub>	2		Α			
Pulsed Drain Current (note1)	I <sub>DM</sub>	8			Α		
Gate-Source Voltage	$V_{GSS}$	±30		V			
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	45		mJ			
Avalanche Current (note1)	I <sub>AS</sub>	3		Α			
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	27		mJ			
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	25		70	W		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C			

Thermal Resistance						
Bergmater	Symbol		l lmit			
Parameter		TO-220F	TO-220	TO-263	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	5	1.78		K/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60		r\/ VV	



<b>Specifications</b> $T_J = 25^{\circ}C$ , ur  Parameter	Symbol		Value			
		Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	900			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 900V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C			1	
		$V_{DS} = 720V, V_{GS} = 0V, T_{J} = 125^{\circ}C$			100	- μA
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> =1A		5	6	Ω
Dynamic						
Input Capacitance	C <sub>iss</sub>	V 0V		424		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		46		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		8		
Total Gate Charge	$Q_g$			16		nC
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 720V, I_{D} = 2A, V_{GS} = 10V$		6		
Gate-Drain Charge	$Q_{gd}$	- 55		2		
Turn-on Delay Time	t <sub>d(on)</sub>			35		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 450V, I_{D} = 2A,$		12		ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		102		
Turn-off Fall Time	t <sub>f</sub>			41		
Drain-Source Body Diode Character	istics					
Continuous Body Diode Current	I <sub>S</sub>	T 0500			2	۸
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			8	А
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C$ , $I_{SD} = 1A$ , $V_{GS} = 0V$			1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_S = 2A,$		397		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		0.5		μC

#### **Notes**

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

#### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )

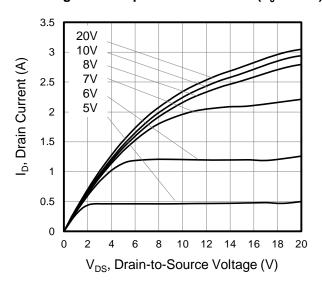


Figure 3. Drain Current vs. Temperature

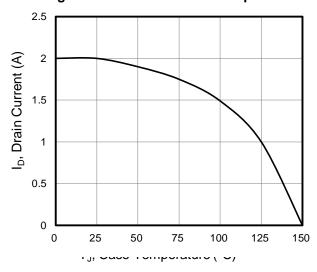


Figure 5. Transfer Characteristics

T<sub>J</sub> = 25°C

T<sub>J</sub> = 25°C

T<sub>J</sub> = 150°C

T<sub>J</sub> = 150°C

V<sub>GS</sub>, Gate-to-Source Voltage (V)

Figure 2. Body Diode Forward Voltage

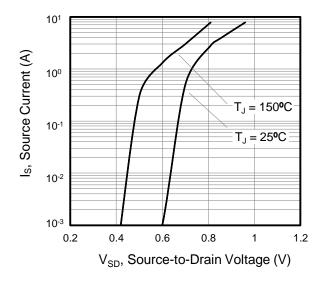


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

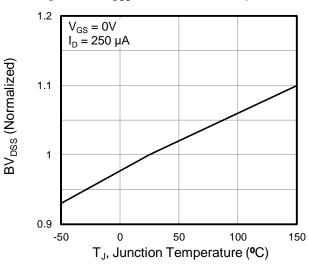
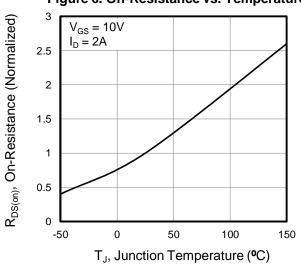


Figure 6. On-Resistance vs. Temperature



#### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

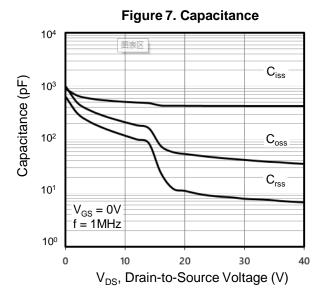


Figure 9. Transient Thermal Impedance

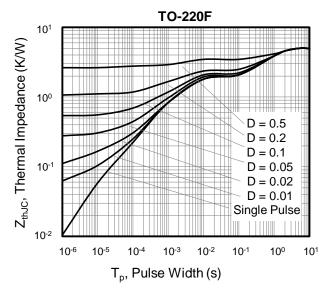


Figure 8. Gate Charge

10

V<sub>DD</sub> = 160V

V<sub>DD</sub> = 400V

V<sub>DD</sub> = 640V

V<sub>DD</sub> = 640V

Q<sub>Q</sub>, Total Gate Charge (nC)

Figure 10. Transient Thermal Impedance

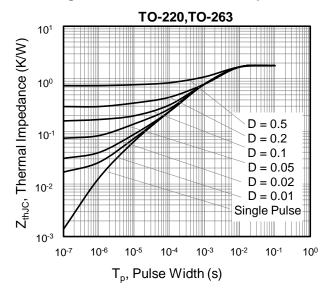


Figure A: Gate Charge Test Circuit and Waveform

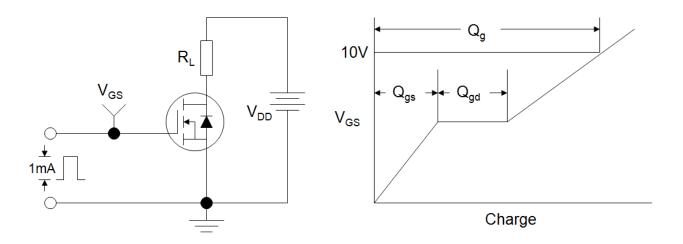


Figure B: Resistive Switching Test Circuit and Waveform

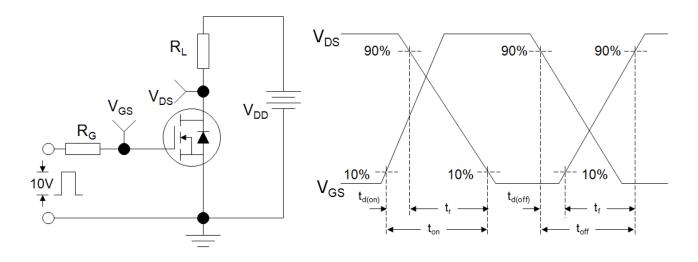
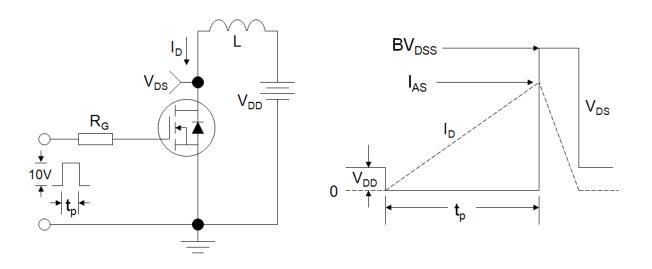
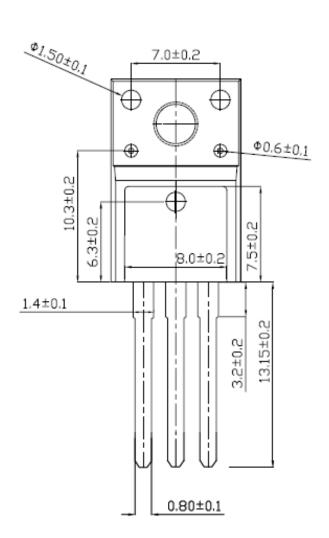


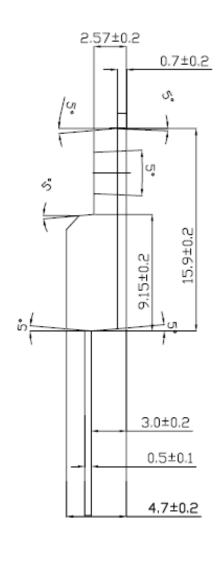
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





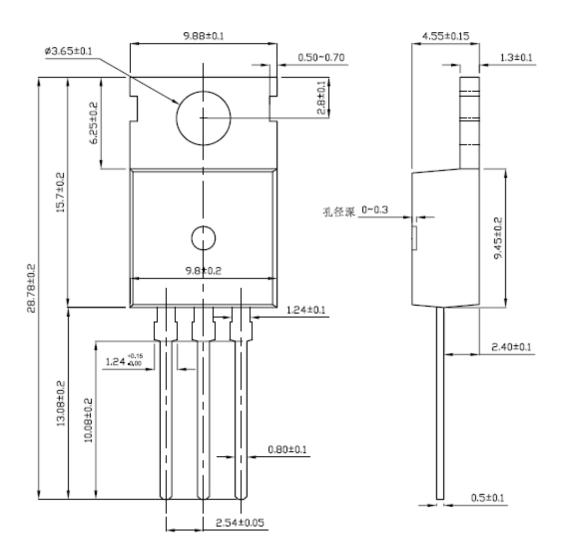
#### **TO-220F**





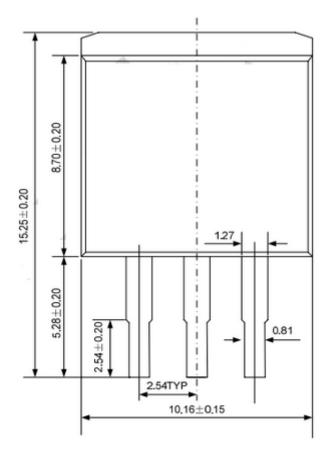


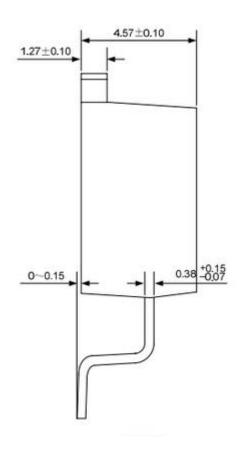
#### **TO-220**





# **TO-263**







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